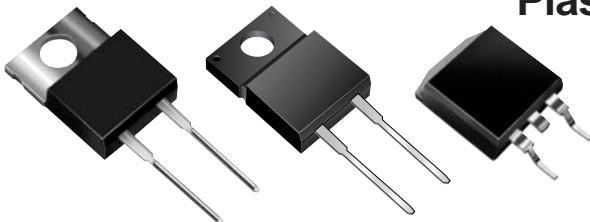
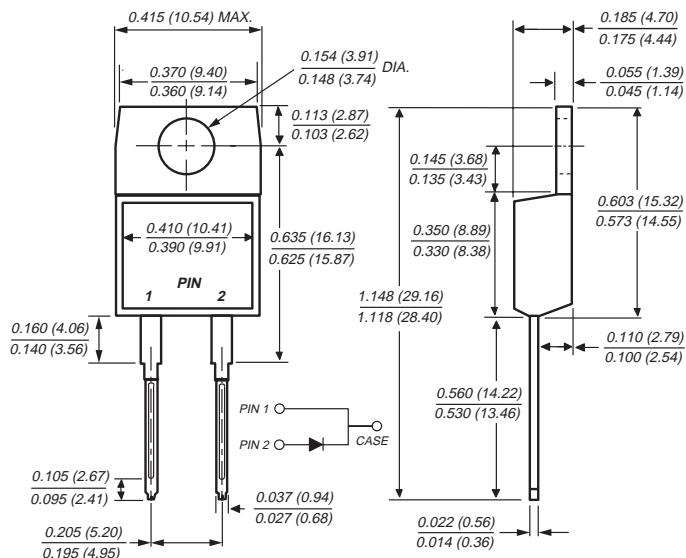


Glass Passivated General Purpose Plastic Rectifier

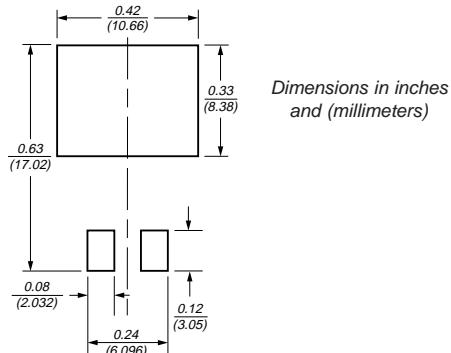
Reverse Voltage 50 to 1000
Forward Current 8.0A



TO-220AC (NSxT)



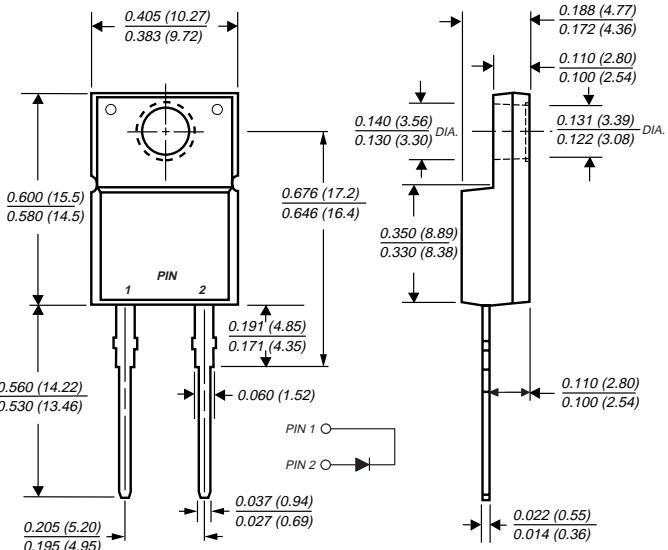
Mounting Pad Layout TO-263AB



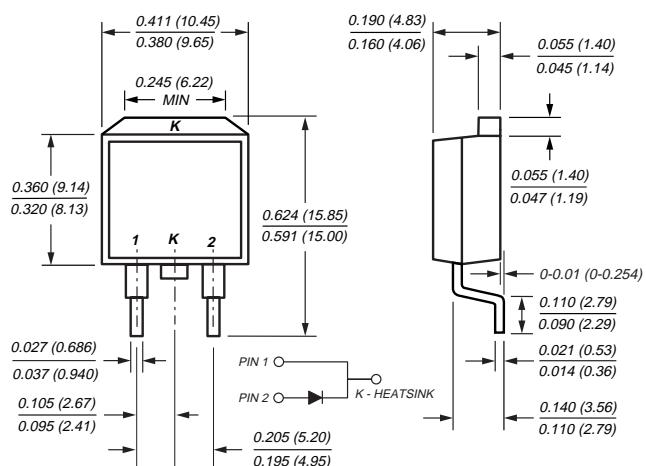
Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
 - High forward current capability
 - High surge current capability
 - Low forward voltage drop
 - Glass passivated chip junction
 - High temperature soldering guaranteed:
260°C/10 seconds, 0.160" (4.06mm) lead length

ITO-220AC (NSFxT)



TO-263AB (NSBxT)



Mechanical Data

Case: JEDEC TO-220AC, ITO-220AC & TO-263AB molded plastic body

Terminals: Plated leads solderable per MIL-STD-750, Method 2026

Polarity: As marked

Mounting Torque: 10 in. -lbs. max.

Mounting Position: Any

Weight: 0.064 ounce, 1.81 grams

NSxT, NSFxt, NSBxt

Vishay Semiconductors
formerly General Semiconductor



Maximum Ratings & Thermal Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbols	NS8 AT	NS8 BT	NS8 DT	NS8 GT	NS8 JT	NS8 KT	NS8 MT	Units
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at T _c =100°C	I _{F(AV)}				8.0				A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}				125				A
Operating junction and storage temperature range	T _J , T _{STG}				-55 to +150				°C
RMS Isolation voltage (NSF type only) from terminals to heatsink with t = 1.0 second, RH ≤ 30%	V _{ISOL}				4500 ⁽¹⁾ 3500 ⁽²⁾ 1500 ⁽³⁾				V

Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbols	NS8 AT	NS8 BT	NS8 DT	NS8 GT	NS8 JT	NS8 KT	NS8 MT	Units
Maximum instantaneous forward voltage at 8.0A	V _F				1.1				V
Maximum DC reverse current at rated DC blocking voltage	I _R				10				µA
Typical junction capacitance at 4.0V, 1MHz	C _J				55				pF

Thermal Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbols	NSxT	NSFxt	NSBxt	Units
Typical thermal resistance ⁽⁴⁾	R _{θJC}	3.0	5.0	3.0	°C/W

Notes:

- (1) Clip mounting (on case), where lead does not overlap heatsink with 0.110" offset
- (2) Clip mounting (on case), where leads do overlap heatsink
- (3) Screw mounting with 4-40 screw, where washer diameter is ≤ 4.9mm (0.19")
- (4) Thermal resistance from junction to case mounted on heat sink

Ratings and Characteristic Curves

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig. 1 – Forward Current Derating Curve

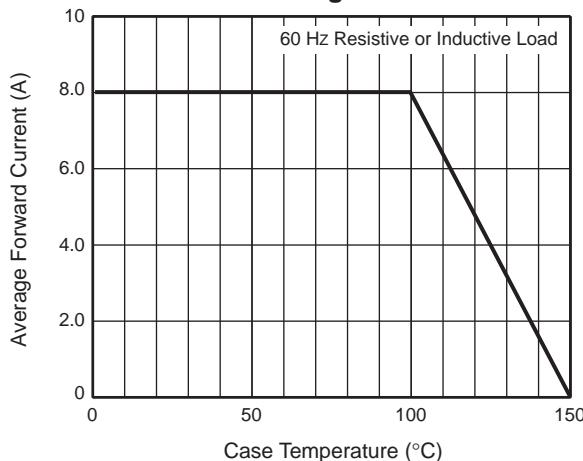


Fig. 2 – Maximum Non-Repetitive Peak Forward Surge Current

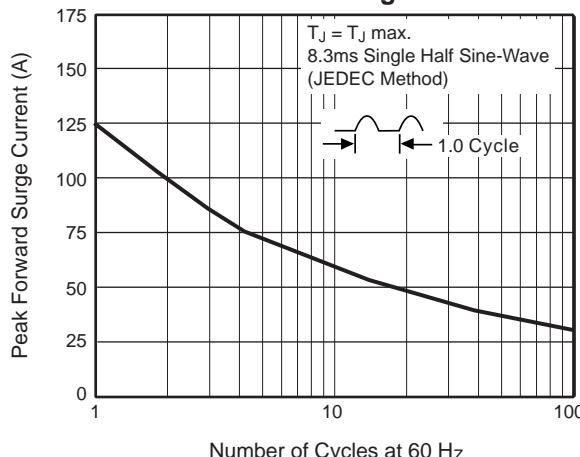


Fig. 3 – Typical Instantaneous Forward Characteristics

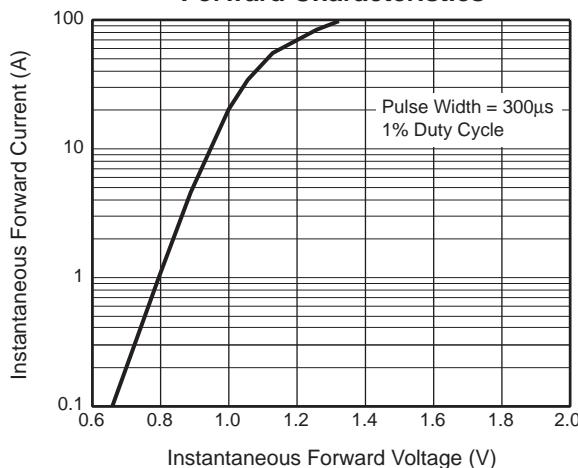


Fig. 4 – Typical Reverse Characteristics

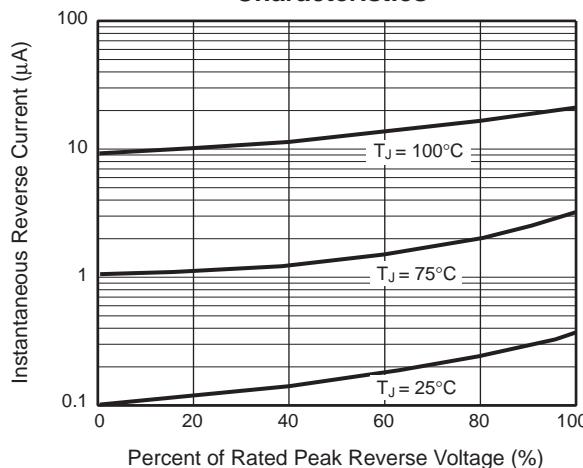


Fig. 5 – Typical Junction Capacitance Per Leg

